

# SLR Fluorine Etcher: recipe = SiVertHF

(developed by Bill Mitchell, Nanofab process group)

<b><u>Substrate structure</u></b>	<i>Si(500nm)/SiO2(2000nm)/Si(sub0</i>	
<b><u>Masking resist</u></b>	<i>maN-2405(~120nm)</i>	
<b><u>Plasma Powers</u></b>	<b>ICP</b>	<i>950W</i>
	<b>CCP[bias]</b>	<i>15W</i>
<b><u>Gas Flows</u></b>	<b>C4F8</b>	<i>60sccm</i>
	<b>SF6</b>	<i>24sccm</i>
	<b>CF4</b>	<i>27sccm</i>
<b><u>Gas Pressures</u></b>	<b>Etch step</b>	<i>20mTorr</i>
	<b>Ignition step</b>	<i>10mTorr (SF6 flow set low to 10sccm)</i>
<b><u>Etch Data</u></b>		
<b>Etch Rate</b> (laser monitor)	<i>Si ~ 300-350nm/min, SiO2 ~ 30-35nm/min</i>	
<b>Etch angle</b>	<i>~89-90 degrees</i>	

